3. The apparatus of claim 1, wherein said suction cutouts are concentrically arranged and formed as one of trenches and holes distributed on said contact region.

4. The apparatus of claim 3, wherein said suction cutouts are arranged uniformly about said contact region.

5. The apparatus of claim 1, wherein ~~said~~ Peltier element is capable of varying the temperature of the adhesive film by at least about 20° C.

6. A removal device for removing at least one chip-type semiconductor component from an adhesive film having first and second main surfaces, wherein the chip-type semiconductor component is arranged on the first main surface of the adhesive film, the removal device comprising:

a lifting device configured to be arranged at the second main surface of the adhesive film, wherein said lifting device has a contact region for arrangement with respect to the adhesive film, said contact region having, for its part, a plurality of first, suction, cutouts and second cutouts configured to receive pin-type lifting means;

said lifting device further including a Peltier element for changing the temperature of the adhesive film;

wherein at least some of said suction cutouts are connected to a vacuum regulating device.

7. The removal device of claim 6, wherein said at least some of said suction cutouts are connected to a single vacuum regulating device.

8. The removal device of claim 7, wherein all of said suction cutouts are connected to said single vacuum regulating device.

9. The removal device of claim 7, wherein groups of said suction cutouts are connected to separate vacuum regulating devices.

3. The apparatus of claim 1, wherein said suction cutouts are concentrically arranged and formed as one of trenches and holes distributed on said contact region.

4. The apparatus of claim 3, wherein said suction cutouts are arranged uniformly about said contact region.

5. The apparatus of claim 1, wherein a Peltier element is capable of varying the temperature of the adhesive film by at least about 20° C.

6. A removal device for removing at least one chip-type semiconductor component from an adhesive film having first and second main surfaces, wherein the chip-type semiconductor component is arranged on the first main surface of the adhesive film, the removal device comprising:

a lifting device configured to be arranged at the second main surface of the adhesive film, wherein said lifting device has a contact region for arrangement with respect to the adhesive film, said contact region having, for its part, a plurality of first, suction, cutouts and second cutouts configured to receive pin-type lifting means;

said lifting device further including a Peltier element for changing the temperature of the adhesive film;

wherein at least some of said suction cutouts are connected to a vacuum regulating device.

7. The removal device of claim 6, wherein said at least some of said suction cutouts are connected to a single vacuum regulating device.

8. The removal device of claim 7, wherein all of said suction cutouts are connected to said single vacuum regulating device.

9. The removal device of claim 7, wherein groups of said suction cutouts are connected to separate vacuum regulating devices.